

➤ Features

- Size 0.08*0.05 inch /2.0*1.2 mm
- RoHS compliant, lead-free and halogen-free
- Fast response to fault current
- Low resistance
- Low-profile
- Compatible with high temperature solders

➤ Applications

- Computer, Mobile phones, Multimedia
- Automotive, Industrial controls, Telephony and broadband
- Game machines, Portable electronics, Battery

➤ Electrical Characteristics (25°C)

Part Number	I _{hold}	I _{trip}	V _{max}	I _{max}	P _d	Time to trip		R _{min}	R _{Imax}
	(A)	(A)	(V)	(A)	(W)	(A)	(S)	(Ω)	(Ω)
BSMD0805L-075	0.75	1.5	6.0	50	1.0	8.0	0.3	0.009	0.070
BSMD0805L-110	1.10	2.2	6.0	50	1.0	8.0	0.5	0.008	0.065
BSMD0805L-125	1.25	2.5	6.0	50	1.0	8.0	1.0	0.007	0.060
BSMD0805L-150	1.50	3.0	6.0	50	1.0	8.0	5.0	0.006	0.055
BSMD0805L-175	1.75	3.5	6.0	50	1.0	8.0	5.0	0.005	0.050
BSMD0805L-200	2.00	4.0	6.0	50	1.0	8.0	5.0	0.004	0.045
BSMD0805L-260	2.60	5.2	6.0	50	1.0	12.0	5.0	0.003	0.035
BSMD0805L-300	3.00	6.0	6.0	50	1.0	12.0	5.0	0.003	0.030
BSMD0805L-350	3.50	7.0	6.0	50	1.0	12.0	5.0	0.002	0.025
BSMD0805L-380	3.80	7.6	6.0	50	1.0	12.0	5.0	0.002	0.020

I_{hold} = Hold current: maximum current device will pass without tripping in 25°C still air.

I_{trip} = Trip current: minimum current at which the device will trip in 25°C still air.

V_{max} = Maximum voltage device can withstand without damage at rated current (I_{max})

I_{max} = Maximum fault current device can withstand without damage at rated voltage (V_{max})

P_{d typ.} = Typical power dissipated from device when in the tripped state at 25°C still air.

R_{min} = Minimum resistance of device in initial (un-soldered) state.

R_{Imax} = Maximum resistance of device at 25°C measured one hour after tripping or reflow soldering of 260°C for 20 sec.

Caution: Operation beyond the specified ratings may result in damage and possible arcing and flame.

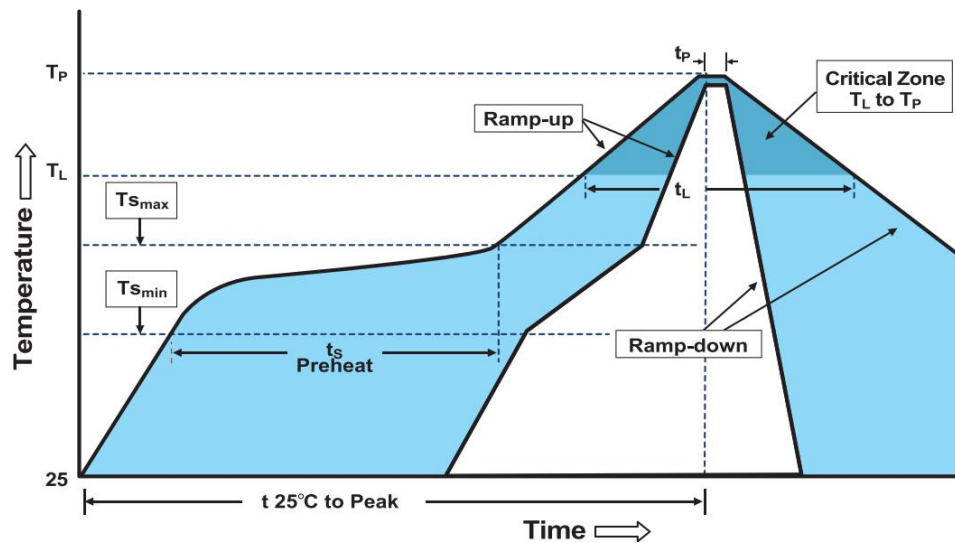
➤ WARNING

- Users shall independently assess the suitability of these devices for each of their applications.
- Operation of these devices beyond the stated maximum ratings could result in damage to the devices and lead to electrical arcing and/or fire.
- These devices are intended to protect against the effects of temporary over-current or over-temperature conditions and are not intended to perform as protective devices where such conditions are expected to be repetitive or prolonged in duration.
- Exposure to silicon-based oils, solvents, electrolytes, acids, and similar materials can adversely affect the performance of these PPTC devices.
- These devices undergo thermal expansion under fault conditions, and thus shall be provided with adequate space and be protected against mechanical stresses.
- Circuits with inductance may generate a voltage ($L di/dt$) above the rated voltage of the PPTC device.

➤ Thermal Derating Chart

Part Number	Ambient operating temperature hold current(I_{hold})							
	-40°C	-20°C	0°C	25°C	40°C	50°C	60°C	70°C
BSMD0805L-075	1.1	1.0	0.8	0.75	0.7	0.6	0.5	0.4
BSMD0805L-110	1.7	1.4	1.2	1.10	1.0	0.8	0.7	0.6
BSMD0805L-125	1.9	1.6	1.4	1.25	1.1	0.9	0.8	0.7
BSMD0805L-150	2.3	2.0	1.7	1.50	1.4	1.1	1.0	0.9
BSMD0805L-175	2.6	2.3	1.9	1.75	1.6	1.2	1.1	1.0
BSMD0805L-200	3.0	2.6	2.2	2.00	1.8	1.4	1.3	1.2
BSMD0805L-260	3.9	3.4	2.9	2.60	2.3	1.8	1.7	1.6
BSMD0805L-300	4.5	3.9	3.3	3.00	2.7	2.1	2.0	1.8
BSMD0805L-350	5.3	4.6	3.9	3.50	3.2	2.5	2.3	2.1
BSMD0805L-380	5.7	4.9	4.2	3.80	3.4	2.7	2.5	2.3

➤ Soldering Parameters



Profile Feature	Pb-Free Assembly
Average Ramp-Up Rate($T_{s_{max}}$ to T_p)	3°C/second max
Preheat	
-Temperature Min($T_{s_{min}}$)	150°C
-Temperature Max($T_{s_{max}}$)	200°C
-Time($T_{s_{min}}$ to $T_{s_{max}}$)	60~180 seconds
Time maintained above:	
-Temperature(T_L)	217°C
-Time(t_L)	60~150 seconds
Peak Temperature(T_p)	260°C
Ramp-Down Rate	6°C/second max
Time 25°C to Peak Temperature	8 minutes max
Storage Condition	0°C~30°C, 30%-60%RH

- Recommended reflow methods: IR, vapor phase oven, hot air oven, N2 environment for lead-free.
- Recommended maximum paste thickness is 0.25mm.
- Devices can be cleaned using standard industry methods and solvents.

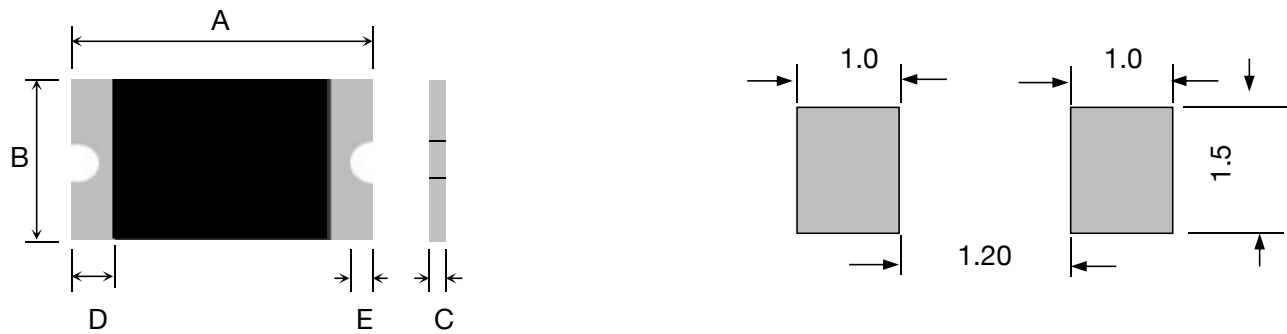
Note 1: All temperature refer to topside of the package, measured on the package body surface.

Note 2: If reflow temperatures exceed the recommended profile, devices may not meet the performance requirements.

➤ Environmental Specifications

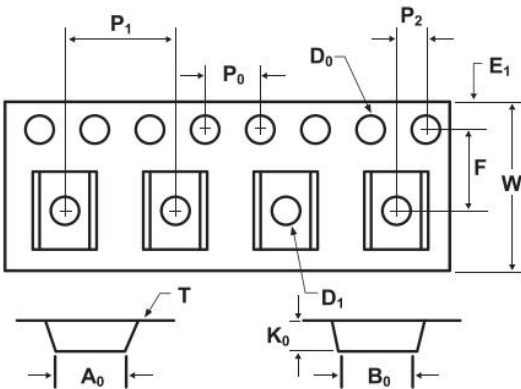
Test	Conditions	Resistance change
Passive aging	+85°C, 1000 hrs.	±5% typical
Humidity aging	+85°C, 85% R.H. , 168 hours	±5% typical
Thermal shock	+85°C to -40°C, 20 times	±33% typical
Resistance to solvent	MIL-STD-202,Method 215	No change
Vibration	MIL-STD-202,Method 201	No change
Ambient operating conditions : - 40 °C to +85 °C		
Maximum surface temperature of the device in the tripped state is 125 °C		

➤ Physical Dimensions & Recommended Pad Layout (mm)



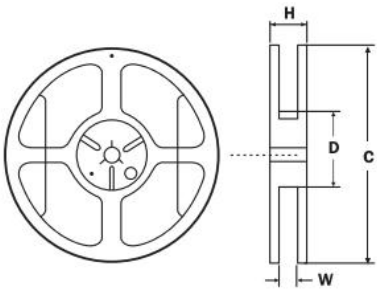
Part Number	Quantity	A		B		C		D	E
		Min	Max	Min	Max	Min	Max	Min	Min
BSMD0805L-075	4000	--	2.50	--	1.80	--	0.8	0.20	0.10
BSMD0805L-110	4000	--	2.50	--	1.80	--	0.8	0.20	0.10
BSMD0805L-125	4000	--	2.50	--	1.80	--	0.8	0.20	0.10
BSMD0805L-150	4000	--	2.50	--	1.80	--	0.8	0.20	0.10
BSMD0805L-175	4000	--	2.50	--	1.80	--	0.8	0.20	0.10
BSMD0805L-200	4000	--	2.50	--	1.80	--	1.0	0.20	0.10
BSMD0805L-260	4000	--	2.50	--	1.80	--	1.0	0.20	0.10
BSMD0805L-300	4000	--	2.50	--	1.80	--	1.0	0.20	0.10
BSMD0805L-350	3000	--	2.50	--	1.80	--	1.2	0.20	0.10
BSMD0805L-380	3000	--	2.50	--	1.80	--	1.2	0.20	0.10

➤ **Tape And Reel Specifications (mm)**



Governing Specifications	BSMD0805L-075~ BSMD0805L-175	BSMD0805L-200~ BSMD0805L-300	BSMD0805L-350~ BSMD0805L-800
W	8.0 ± 0.3	8.0 ± 0.3	8.0 ± 0.3
F	3.5 ± 0.05	3.5 ± 0.05	3.5 ± 0.05
E1	1.75 ± 0.1	1.75 ± 0.1	1.75 ± 0.1
D0	1.55 ± 0.05	1.55 ± 0.05	1.55 ± 0.05
D1	1.0 ± 0.1	1.0 ± 0.1	1.0 ± 0.1
P0	4.0 ± 0.1	4.0 ± 0.1	4.0 ± 0.1
P1	4.0 ± 0.1	4.0 ± 0.1	4.0 ± 0.1
P2	2.0 ± 0.05	2.0 ± 0.05	2.0 ± 0.05
A0	1.6 ± 0.1	1.6 ± 0.1	1.6 ± 0.1
B0	2.3 ± 0.1	2.3 ± 0.1	2.3 ± 0.1
T	0.2 ± 0.1	0.2 ± 0.1	0.2 ± 0.1
K0	0.74 ± 0.1	1.04 ± 0.1	1.35 ± 0.1
Leader _{min}	390	390	390
Trailer _{min}	160	160	160

Reel Dimensions	
C	φ178 ± 1.0
D	φ60.2 ± 0.5
H	11.0 ± 0.5
W	9.0 ± 1.5



➤ **Contact information**

SHENZHEN BHFUSE INDUSTRIAL CO., LTD
TEL: 0755-85259917 FAX: 0755-28704432
E-MAIL: sales@bhfuse.com